

- NOTES:
- MATERIAL:
    - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:NATURAL OR BLACK.
    - CONTACT: COPPER ALLOY
    - FITTING NAIL:COPPER ALLOY
  - FINISH:
    - CONTACT: UNDERPLATING: 50 $\mu$ " MIN. NICKEL OVERALL. FINISH:GOLD FLASH PLATING GOLD 3 $\mu$ " MIN. ON CONTACT
    - FITTING NAIL: UNDERPLATING: 50 $\mu$ " MIN. NICKEL OVERALL. FINISH:GOLD FLASH PLATING
  - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
  - ROHS COMPLIANT PRODUCT.
  - SPEC. PLS. REFER TO PS-88881-xxxxx
  - DRAWING PACKAGING REFER TO 88882-xxxx
  - COPLANARITY 0.1 MM MAX. BASE ON DATUM A
  - TRUE POSITION 0.1 MM MAX. BAES ON DATUM B
  - PART NUMBER

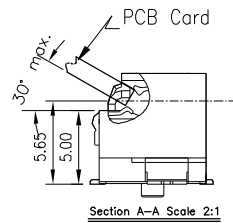
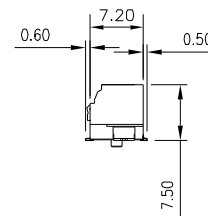
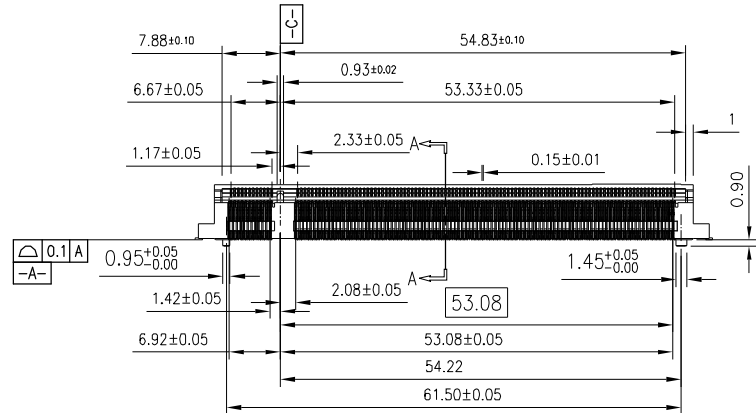
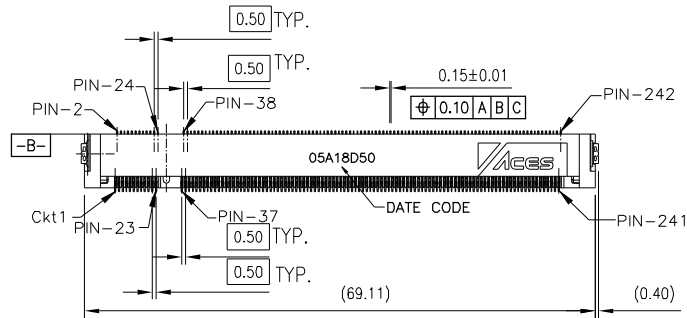
88882-2D X X-XXX

XXX	Housing Color.	PACKING
002	NATURAL	88882-2DCR-U

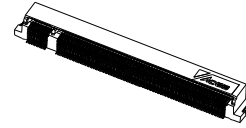
NO OF CKT 230 CKTS

PACKING 0:Tape & Reel 2:Tray

PLATING 8: G/F (LEAD FREE) GOLD 3 $\mu$ " MIN. ON CONTACT M:3 $\mu$ " GOLD ON CONTACT AND SOLDER FOR SELECRIEENESS PLATING K:30 $\mu$ " GOLD ON CONTACT AND SOLDER FOR SELECRIEENESS PLATING T:10 $\mu$ " GOLD ON CONTACT AND SOLDER FOR SELECTIVENESS PLATING

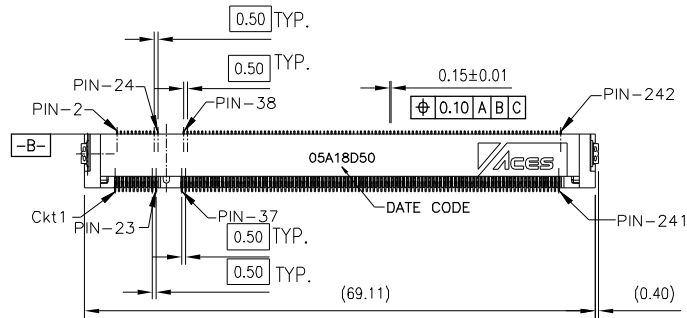


<b>QUALITY SYMBOLS</b> MAJOR Ⓢ CRITICAL Ⓢ <b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X: ±0.5 X: ±0.25 XX: ±0.15 XXX: ±0.1 ANGLES ±2°	DRAWN BY Ding,shuqin	DATE 21/09/01			
	CHECKED BY Lu, Jing Quan	DATE 21/09/01			TITLE MXM 230 pins 0.5mm pitch Edge Card Conn. R/A D/R STD H=7.5mm (B/B H=5.0mm)
	APPROVED BY hsieh, fu yu	DATE 21/09/01	UNITS mm	SIZE A4	RFG NO. N/A
	SCALE 1:1	SHEET NO. 1 OF 4	REV L	DWG NO. 88882-2DXX-XXX	

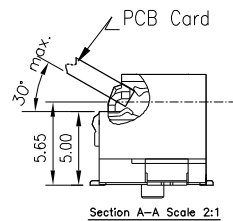
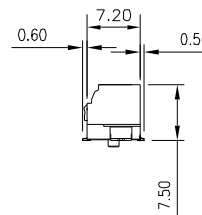
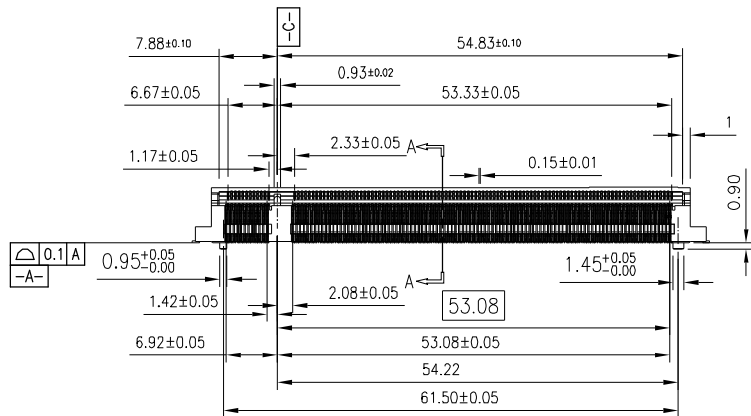


NOTES:

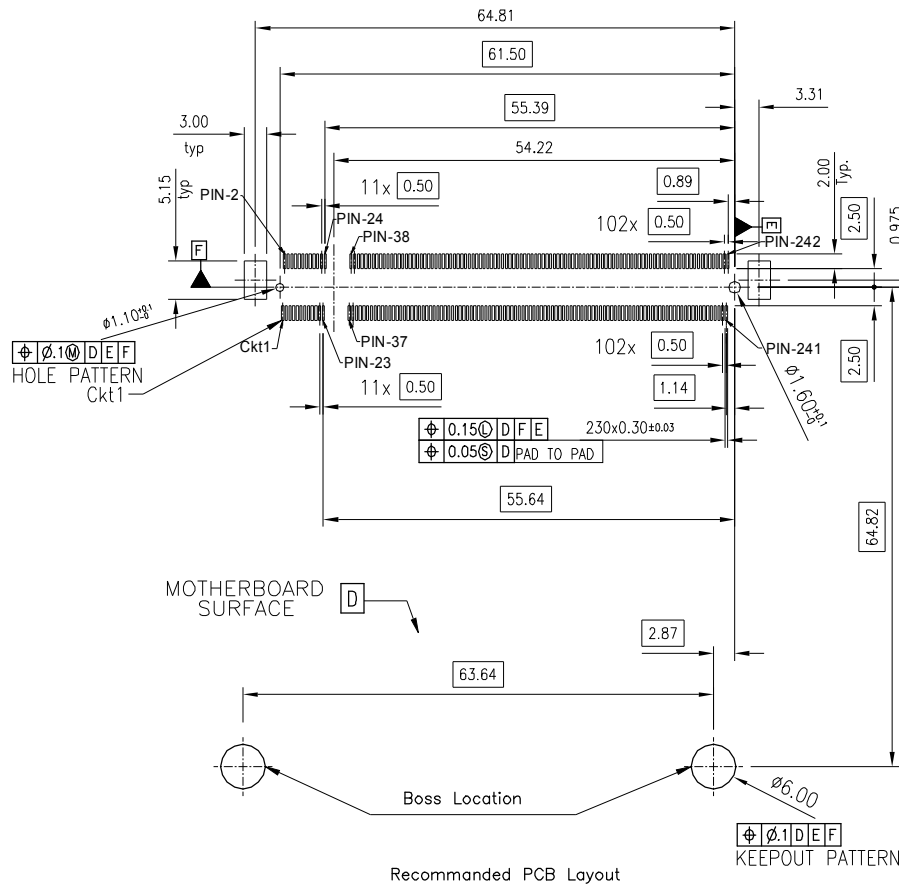
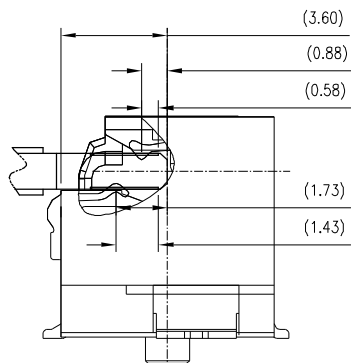
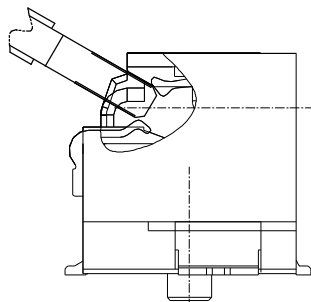
1. MATERIAL:
  - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:NATURAL OR BLACK .
  - 1.2 CONTACT: COPPER ALLOY
  - 1.3 FITTING NAIL:COPPER ALLOY
2. FINISH:
  - 2.1 CONTACT:
    - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
    - FINISH:GOLD FLASH PLATING
    - GOLD 3u" MIN. ON CONTACT
  - 2.2 FITTING NAIL:
    - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
    - FINISH:GOLD FLASH PLATING
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. ROHS COMPLIANT PRODUCT.
5. SPEC. PLS. REFER TO PS-88881-xxxxx
6. DRAWING PACKAGING REFER TO 88882-xxxx
7. COPLANARITY 0.1 MM MAX. BASE ON DATUM A
8. TRUE POSITION 0.1 MM MAX. BAES ON DATUM B
9. PART NUMBER



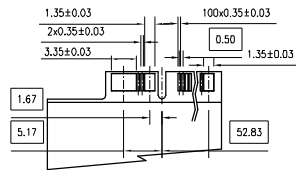
88882-2D T T-001		XXX	Housing Color.
NO OF CKT 230 CKTS		001	BLACK
PACKING T:Tape & Reel(Plastic)		PLATING T:10u" GOLD ON CONTACT AND SOLDER FOR SELECTVENESS PLATING	



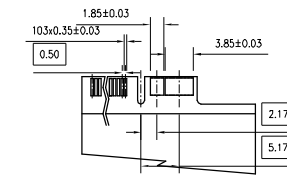
<b>QUALITY SYMBOLS</b> MAJOR Ⓢ CRITICAL Ⓢ <b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X. ±0.5 X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Ding,shuqin CHECKED BY Lu, Jing Quan APPROVED BY hsieh, fu yu	DATE 21/09/01 DATE 21/09/01 DATE 21/09/01		<b>TITLE</b> MXM 230 pins 0.5mm pitch Edge Card Conn. R/A D/R STD H=7.5mm (B/B H=5.0mm)
	UNITS mm SCALE 1:1			



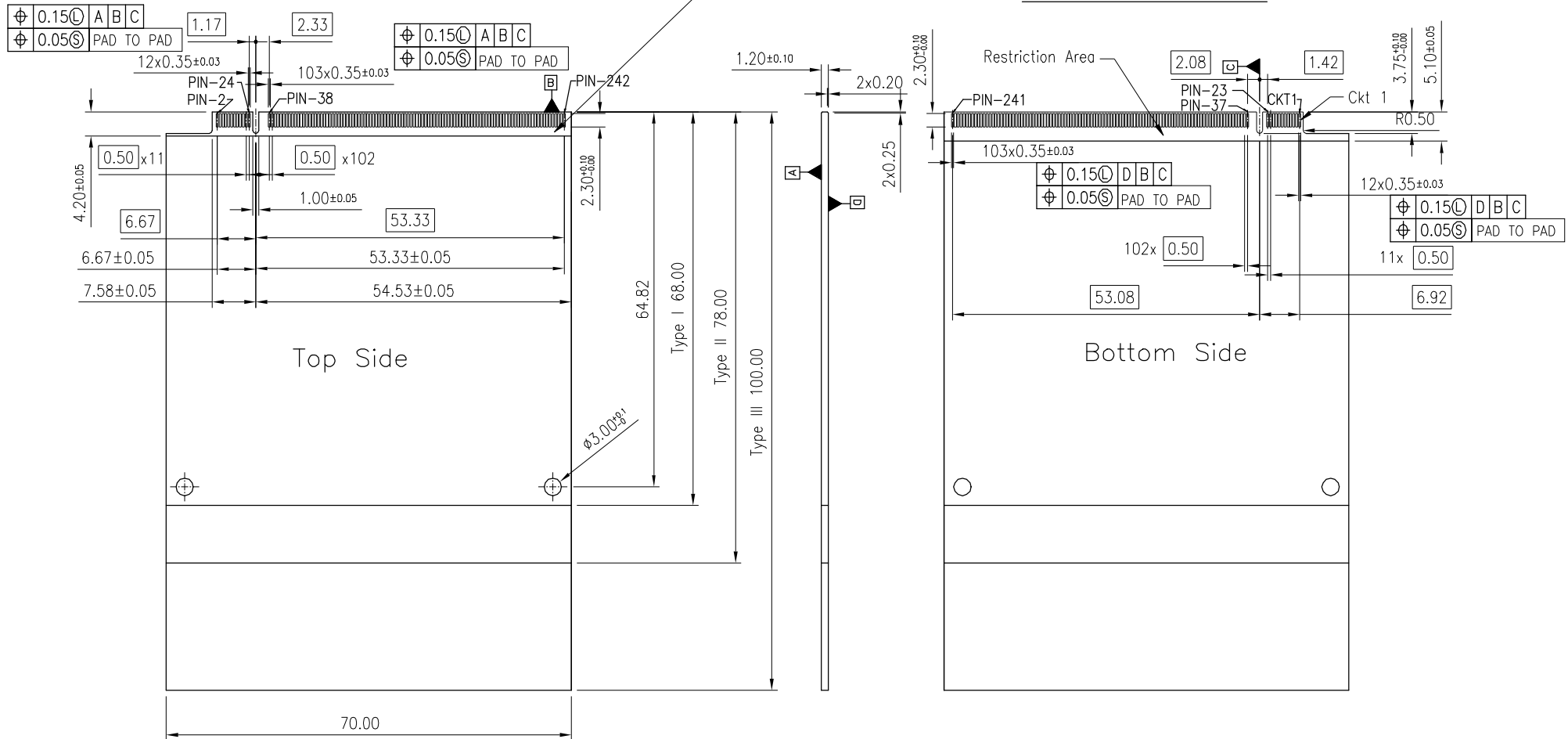
<b>QUALITY SYMBOLS</b> MAJOR Ⓢ CRITICAL Ⓢ <b>GENERAL TOLERANCES</b> ( UNLESS SPECIFIED ) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Ding,shuqin	DATE 21/09/01	
	CHECKED BY Lu, Jing Quan	DATE 21/09/01	
	APPROVED BY hsieh, fu yu	DATE 21/09/01	UNITS mm
	SCALE 1:1	SHEET NO. 3 OF 4	SIZE A4
			RFG NO. N/A
			DWG NO. 88882-2DXX-XXX



Top Side Option one Pad



Bottom Side Option one Pad



Type A Application Card PCB Layout

<b>QUALITY SYMBOLS</b> MAJOR Ⓢ CRITICAL Ⓢ <b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Ding,shuqin DATE 21/09/01	
	CHECKED BY Lu, Jing Quan DATE 21/09/01	
	APPROVED BY hsieh, fu yu DATE 21/09/01	RFG. NO. N/A
	UNITS mm	SIZE A4
	SCALE 1:1	SHEET NO. 4 OF 4
		REV L
		DWG. NO. 88882-2DXX-XXX